

RANDALL G. LOPEZ

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BUSINESS DEVELOPMENT / TECHNICAL MARKETING EXECUTIVE

DESIGN ENGINEERING | PRODUCT DEVELOPMENT | BUILDING AND LEADING EFFECTIVE TEAMS | FORTUNE 500 ACCOUNTS

- Instrumental leader and motivator for cross-functional teams in the USA, Japan, China, Taiwan, Singapore, and Europe
- Received the top award for Toshiba America Electronic Components (TAEC) employees: "Mike Brown Award for Service"
- Two-time recipient of the top award for Six Sigma Management Innovation at TAEC: "President's Award"

PROFESSIONAL HISTORY

Executive Technology Solutions, Inc. - Technical Consulting

2016 to Present

- Technical Consulting, R&D, Analytics for HPC, Consumer, Mobile, Wearable, IoT, Datacenter, and Cloud applications
- Artificial Intelligence, High-Performance Computing, SSD & NAND, Imaging, Audio & Video, Analog Mixed & Signals

TAEC Global Intel Account Technical Director / Consumer & Server Segment Marketing Director

2012 to 2016

- Architected the technical strategy that established Toshiba as a preferred supplier to Intel
- Skyrocketed the annual revenue from the Intel account from \$1M to \$250M in four years
- Boosted design wins by 400% and increased activity from three to over 35 design-wins each year
- Drove multiple integrated circuit and memory design advancements for Intel core and mobile chipsets
- Provided detailed applications engineering support for Intel for NAND, 3D NAND, SSD, and NVMe storage technology
- Drove key innovations including the eDP2DSI MIPI interface chip and the Universal Flash Storage architectures
- Championed technology roadmap alignments across Memory, System LSI, Sensors, and Discrete Technologies

TAEC Global HP Corporation Account Director / Director of Technical Staff & Strategic Marketing

2003 to 2012

- Developed a centralized approach and strengthened the global Hewlett-Packard relationship
- Performed concurrent roles - business development, technical marketing, system architecture, quality assurance engineer
- Established and negotiated the Supplier Partnership 100% Toshiba Share contract for HP's \$11B printing business
- Led semiconductor cumulative volume growth to 3.6 billion in 9 years over 300M cumulative in prior 20 years
- Led cross-functional matrix teams which included HP participants in three hemispheres
- Created the "Assurance of Supply" model to govern the relationship with HP
- Recognized by HP for design innovation: "Tomahawk Special Recognition Award"
- Directed the Toshiba Japan CCD engineering team for HP imaging solutions
- Facilitated the 2011 post-earthquake rescue efforts to save HP "\$2B, 70% market share, and 40,000 global jobs"
- Directed the USA System LSI Business Unit field systems engineering team
- Led the CTO's Strategic Marketing Initiative to conceptualize long-term applications for worldwide markets

TAEC Senior Member Technical Staff for / Director of Technical Staff (Applications Engineering)

1997 to 2003

- Led semiconductor & display design-in efforts for Motorola, Alcatel, Sony, and Sharp Electronics customer applications
- Led the TV, STB, & Mobile applications engineering for TV/Video, Audio, MPEG-4, HDMI, Camera Modules, and Sensors
- Contributed to NAND Flash, NOR Flash, DRAM, Optocouplers, LCD-Drivers, IEEE1394, RF, MCU, ASIC, and System LSIs
- Authored technical application notes and provided quarterly technical training
- Secured the first Toshiba camera design-win at Qualcomm

EDUCATION, PROFESSIONAL AFFILIATIONS, & FOREIGN LANGUAGES

Master of Business Administration (2018) – UNIVERSITY OF NOTRE DAME

Master of Science in Electrical Engineering – UNIVERSITY OF MIAMI

Master of Science in Music Engineering Technology – UNIVERSITY OF MIAMI

Bachelor of Science in Electrical Engineering – UNIVERSITY OF TENNESSEE

Member of IEEE (Institute of Electrical and Electronics Engineers) and the Audio Engineering Society (AES)

Working Knowledge of Japanese and Russian Languages